



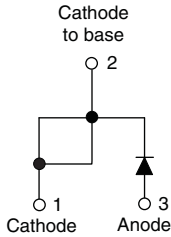
## Ultrafast Soft Recovery Diode, 60 A FRED Pt®



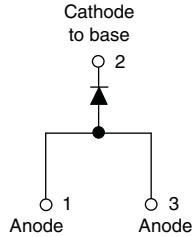
TO-247AC modified



TO-247AC



VS-60EPU06PbF  
VS-60EPU06-N3



VS-60APU06PbF  
VS-60APU06-N3

### FEATURES

- Ultrafast recovery time
- Low forward voltage drop
- 175 °C operating junction temperature
- Designed and qualified according to JEDEC®-JESD47
- Material categorization: for definitions of compliance please see [www.vishay.com/doc?99912](http://www.vishay.com/doc?99912)



### BENEFITS

- Reduced RFI and EMI
- Higher frequency operation
- Reduced snubbing
- Reduced parts count

### DESCRIPTION / APPLICATIONS

These diodes are optimized to reduce losses and EMI/RFI in high frequency power conditioning systems. The softness of the recovery eliminates the need for a snubber in most applications. These devices are ideally suited for HF welding, power converters and other applications where switching losses are not significant portion of the total losses.

PRODUCT SUMMARY	
Package	TO-247AC modified (2 pins), TO-247AC
$I_{F(AV)}$	60 A
$V_R$	600 V
$V_F$ at $I_F$	1.11 V
$t_{rr}$ typ.	See Recovery table
$T_J$ max.	175 °C
Diode variation	Single die

ABSOLUTE MAXIMUM RATINGS				
PARAMETER	SYMBOL	TEST CONDITIONS	MAX.	UNITS
Cathode to anode voltage	$V_R$		600	V
Continuous forward current	$I_{F(AV)}$	$T_C = 116\text{ °C}$	60	A
Single pulse forward current	$I_{FSM}$	$T_C = 25\text{ °C}$	600	
Maximum repetitive forward current	$I_{FRM}$	Square wave, 20 kHz	120	
Operating junction and storage temperatures	$T_J, T_{Stg}$		-55 to +175	°C

ELECTRICAL SPECIFICATIONS ( $T_J = 25\text{ °C}$ unless otherwise specified)						
PARAMETER	SYMBOL	TEST CONDITIONS	MIN.	TYP.	MAX.	UNITS
Breakdown voltage, blocking voltage	$V_{BR}, V_R$	$I_R = 100\text{ }\mu\text{A}$	600	-	-	V
Forward voltage	$V_F$	$I_F = 60\text{ A}$	-	1.35	1.68	
		$I_F = 60\text{ A}, T_J = 125\text{ °C}$	-	1.20	1.42	
		$I_F = 60\text{ A}, T_J = 175\text{ °C}$	-	1.11	1.30	
Reverse leakage current	$I_R$	$V_R = V_R$ rated	-	-	50	$\mu\text{A}$
		$T_J = 150\text{ °C}, V_R = V_R$ rated	-	-	500	
Junction capacitance	$C_T$	$V_R = 600\text{ V}$	-	39	-	pF



DYNAMIC RECOVERY CHARACTERISTICS (T <sub>J</sub> = 25 °C unless otherwise specified)						
PARAMETER	SYMBOL	TEST CONDITIONS	MIN.	TYP.	MAX.	UNITS
Reverse recovery time	t <sub>rr</sub>	I <sub>F</sub> = 1 A, di <sub>F</sub> /dt = 200 A/μs, V <sub>R</sub> = 30 V	-	34	45	ns
		T <sub>J</sub> = 25 °C	-	81	-	
		T <sub>J</sub> = 125 °C	-	164	-	
Peak recovery current	I <sub>RRM</sub>	T <sub>J</sub> = 25 °C	-	7.4	-	A
		T <sub>J</sub> = 125 °C	-	17.0	-	
Reverse recovery charge	Q <sub>rr</sub>	T <sub>J</sub> = 25 °C	-	300	-	nC
		T <sub>J</sub> = 125 °C	-	1394	-	

THERMAL - MECHANICAL SPECIFICATIONS						
PARAMETER	SYMBOL	TEST CONDITIONS	MIN.	TYP.	MAX.	UNITS
Thermal resistance, junction to case	R <sub>thJC</sub>		-	-	0.63	K/W
Thermal resistance, case to heatsink	R <sub>thCS</sub>	Mounting surface, flat, smooth and greased	-	0.2	-	
Weight			-	5.5	-	g
			-	0.2	-	oz.
Mounting torque			1.2 (10)	-	2.4 (20)	N · m (lbf · in)
Marking device		Case style TO-247AC modified	60EPU06			
		Case style TO-247AC	60APU06			

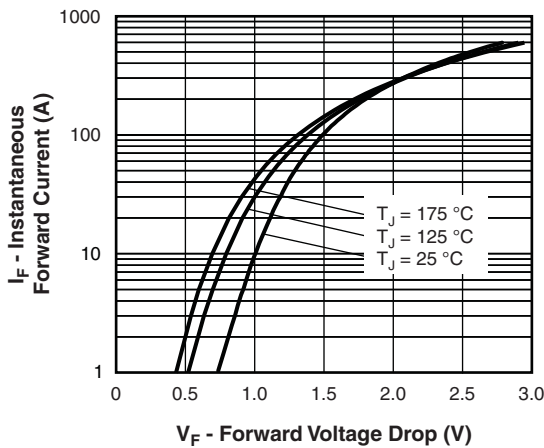


Fig. 1 - Typical Forward Voltage Drop Characteristics

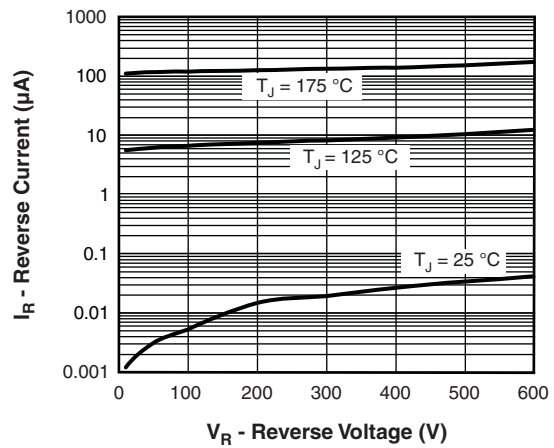


Fig. 2 - Typical Values of Reverse Current vs. Reverse Voltage

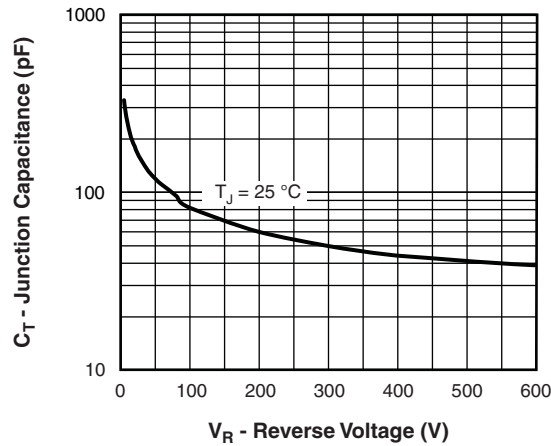


Fig. 3 - Typical Junction Capacitance vs. Reverse Voltage

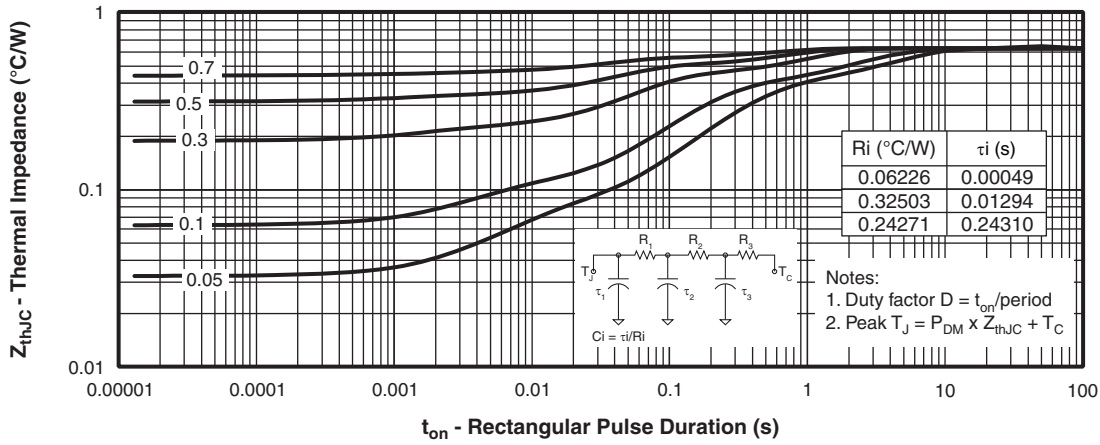


Fig. 4 - Maximum Thermal Impedance  $Z_{thJC}$  Characteristics

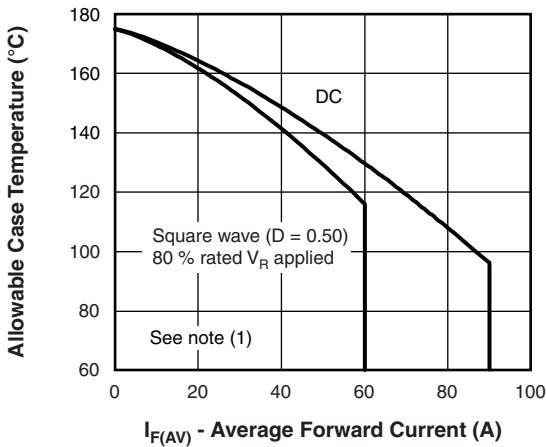


Fig. 5 - Maximum Allowable Case Temperature vs. Average Forward Current

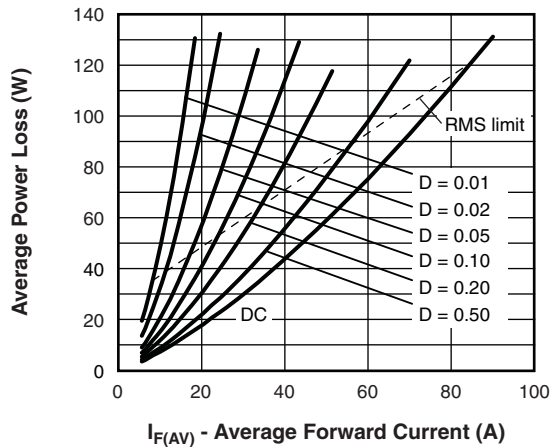


Fig. 6 - Forward Power Loss Characteristics

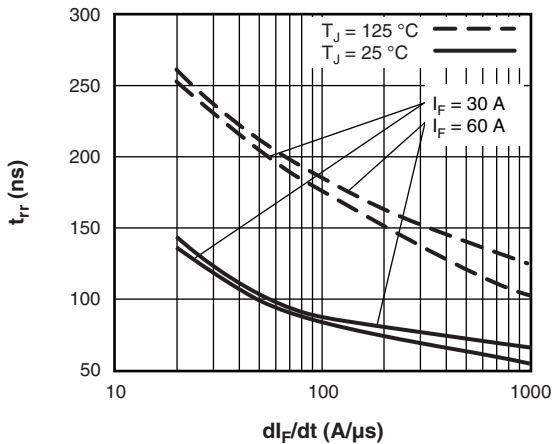


Fig. 7 - Typical Reverse Recovery Time vs.  $di_F/dt$

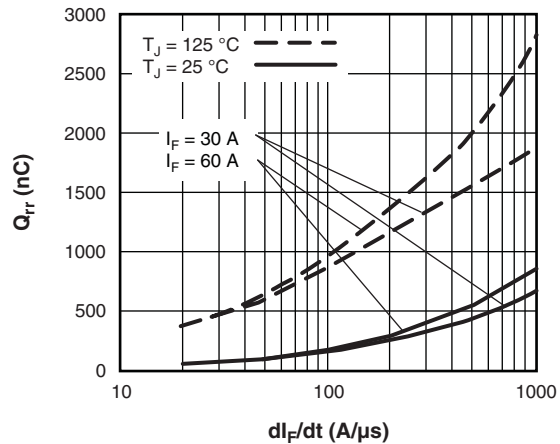


Fig. 8 - Typical Stored Charge vs.  $di_F/dt$

**Note**

- (1) Formula used:  $T_C = T_J - (Pd + Pd_{REV}) \times R_{thJC}$ ;
- $Pd$  = Forward power loss =  $I_{F(AV)} \times V_{FM}$  at  $(I_{F(AV)}/D)$  (see fig. 6);
- $Pd_{REV}$  = Inverse power loss =  $V_{R1} \times I_R (1 - D)$ ;  $I_R$  at  $V_{R1} = 80\%$  rated  $V_R$

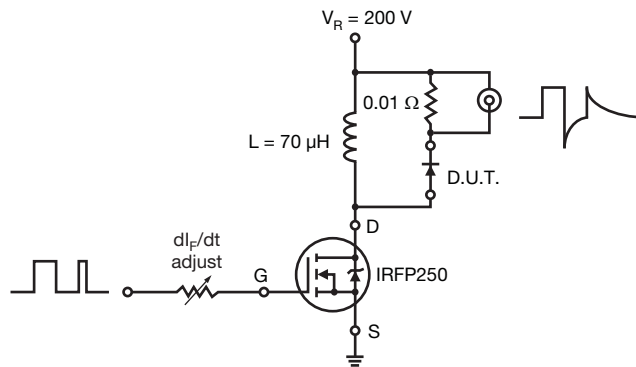
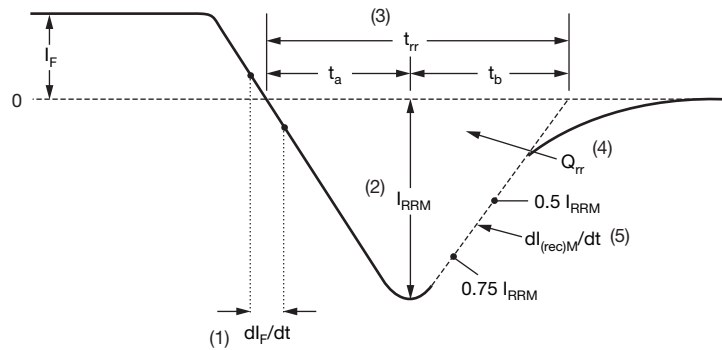


Fig. 9 - Reverse Recovery Parameter Test Circuit



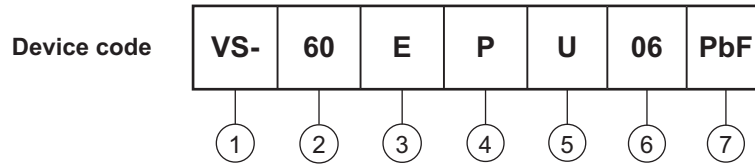
- (1)  $di_F/dt$  - rate of change of current through zero crossing
- (2)  $I_{RRM}$  - peak reverse recovery current
- (3)  $t_{rr}$  - reverse recovery time measured from zero crossing point of negative going  $I_F$  to point where a line passing through  $0.75 I_{RRM}$  and  $0.50 I_{RRM}$  extrapolated to zero current.
- (4)  $Q_{rr}$  - area under curve defined by  $t_{rr}$  and  $I_{RRM}$
- (5)  $dl_{(rec)M}/dt$  - peak rate of change of current during  $t_b$  portion of  $t_{rr}$

$$Q_{rr} = \frac{t_{rr} \times I_{RRM}}{2}$$

Fig. 10 - Reverse Recovery Waveform and Definitions



ORDERING INFORMATION TABLE



- 1** - Vishay Semiconductors product
- 2** - Current rating (60 = 60 A)
- 3** - Circuit configuration:
  - E = single diode
  - A = single diode, 3 pins
- 4** - Package:
  - P = TO-247AC (modified)
- 5** - Type of silicon:
  - U = ultrafast recovery
- 6** - Voltage rating (06 = 600 V)
- 7** - Environmental digit:
  - PbF = lead (Pb)-free and RoHS-compliant
  - N3 = halogen-free, RoHS-compliant and totally lead (Pb)-free

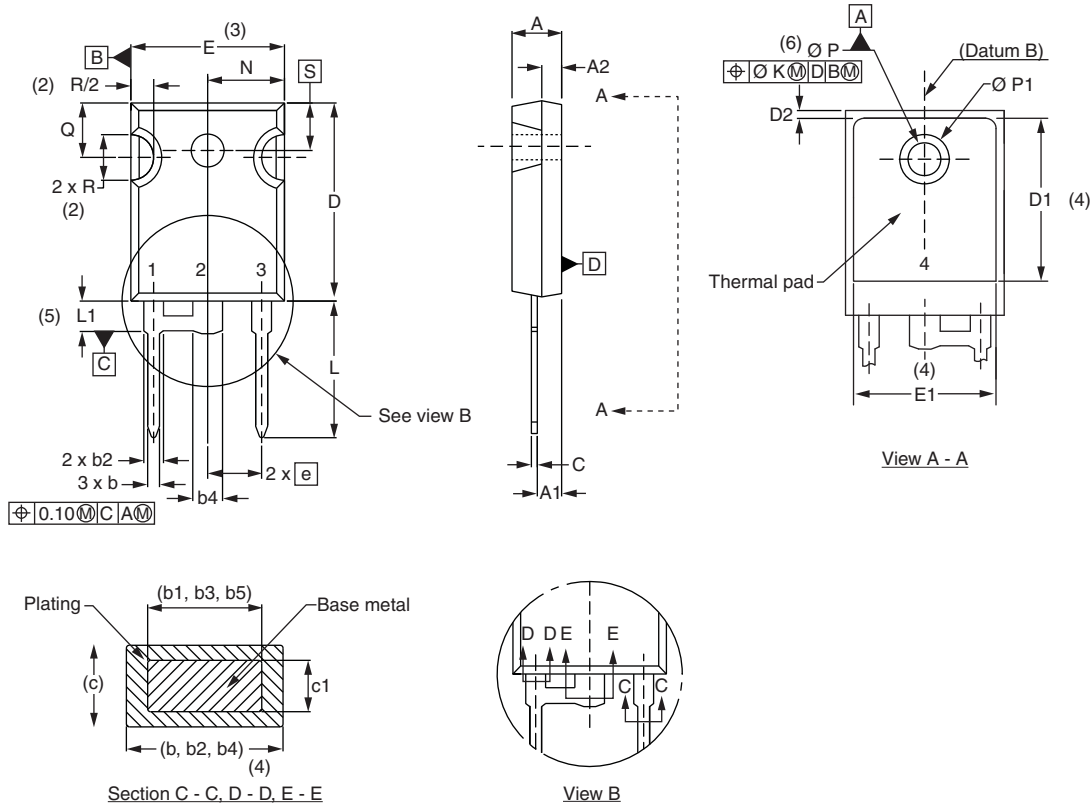
ORDERING INFORMATION (Example)			
PREFERRED P/N	QUANTITY PER T/R	MINIMUM ORDER QUANTITY	PACKAGING DESCRIPTION
VS-60EPU06PbF	25	500	Antistatic plastic tube
VS-60EPU06-N3	25	500	Antistatic plastic tube
VS-60APU06PbF	25	500	Antistatic plastic tube
VS-60APU06-N3	25	500	Antistatic plastic tube

LINKS TO RELATED DOCUMENTS		
Dimensions	TO-247AC modified	<a href="http://www.vishay.com/doc?95541">www.vishay.com/doc?95541</a>
	TO-247AC	<a href="http://www.vishay.com/doc?95542">www.vishay.com/doc?95542</a>
Part marking information	TO-247AC modified PbF	<a href="http://www.vishay.com/doc?95255">www.vishay.com/doc?95255</a>
	TO-247AC modified -N3	<a href="http://www.vishay.com/doc?95442">www.vishay.com/doc?95442</a>
	TO-247ACPbF	<a href="http://www.vishay.com/doc?95226">www.vishay.com/doc?95226</a>
	TO-247AC-N3	<a href="http://www.vishay.com/doc?95007">www.vishay.com/doc?95007</a>



TO-247 - 50 mils L/F modified

**DIMENSIONS** in millimeters and inches



SYMBOL	MILLIMETERS		INCHES		NOTES	SYMBOL	MILLIMETERS		INCHES		NOTES
	MIN.	MAX.	MIN.	MAX.			MIN.	MAX.	MIN.	MAX.	
A	4.65	5.31	0.183	0.209		D2	0.51	1.35	0.020	0.053	
A1	2.21	2.59	0.087	0.102		E	15.29	15.87	0.602	0.625	3
A2	1.17	1.37	0.046	0.054		E1	13.46	-	0.53	-	
b	0.99	1.40	0.039	0.055		e	5.46 BSC		0.215 BSC		
b1	0.99	1.35	0.039	0.053		$\text{Ø K}$	0.254		0.010		
b2	1.65	2.39	0.065	0.094		L	14.20	16.10	0.559	0.634	
b3	1.65	2.34	0.065	0.092		L1	3.71	4.29	0.146	0.169	
b4	2.59	3.43	0.102	0.135		N	7.62 BSC		0.3		
b5	2.59	3.38	0.102	0.133		$\text{Ø P}$	3.56	3.66	0.14	0.144	
c	0.38	0.89	0.015	0.035		$\text{Ø P1}$	-	7.39	-	0.291	
c1	0.38	0.84	0.015	0.033		Q	5.31	5.69	0.209	0.224	
D	19.71	20.70	0.776	0.815	3	R	4.52	5.49	0.178	0.216	
D1	13.08	-	0.515	-	4	S	5.51 BSC		0.217 BSC		

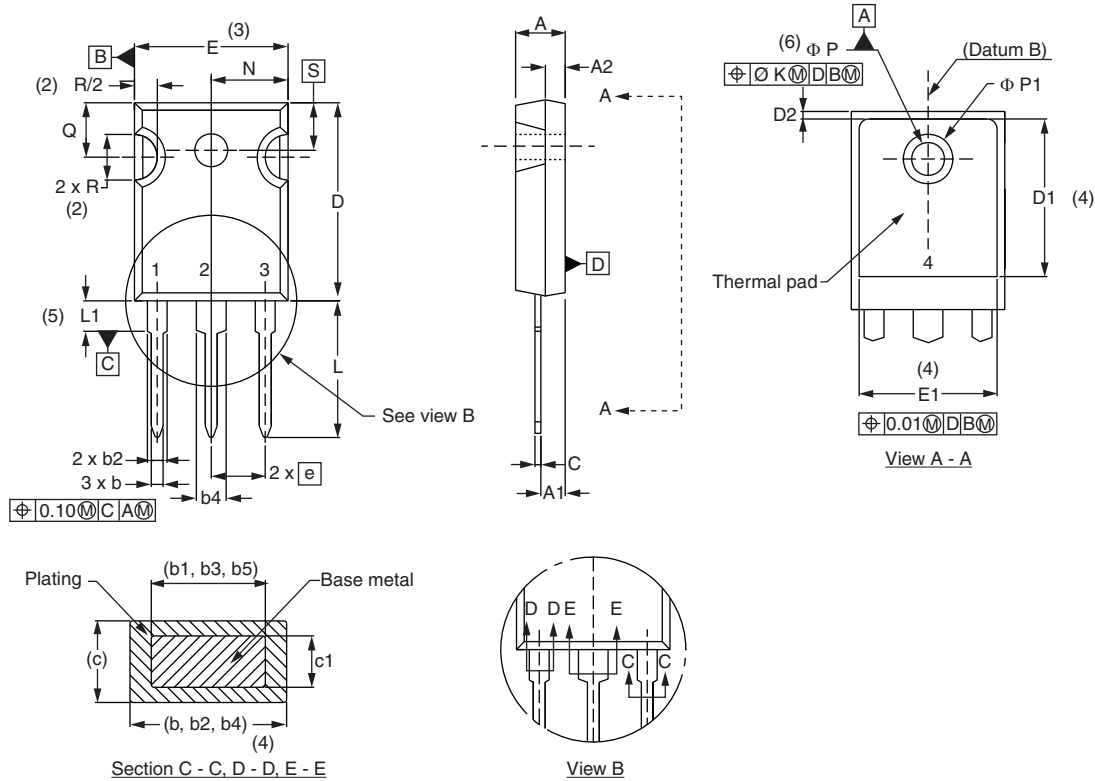
**Notes**

- (1) Dimensioning and tolerance per ASME Y14.5M-1994
- (2) Contour of slot optional
- (3) Dimension D and E do not include mold flash. Mold flash shall not exceed 0.127 mm (0.005") per side. These dimensions are measured at the outermost extremes of the plastic body
- (4) Thermal pad contour optional with dimensions D1 and E1
- (5) Lead finish uncontrolled in L1
- (6)  $\text{Ø P}$  to have a maximum draft angle of 1.5 to the top of the part with a maximum hole diameter of 3.91 mm (0.154")
- (7) Outline conforms to JEDEC® outline TO-247 with exception of dimension c and Q



TO-247 - 50 mils L/F

**DIMENSIONS** in millimeters and inches



SYMBOL	MILLIMETERS		INCHES		NOTES	SYMBOL	MILLIMETERS		INCHES		NOTES
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